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**Reply under 37 CFR 1.116
Expedited Procedure
Examining Group 1753**

Appl. No.:	10/672,416	Confirmation No.:	8435
Applicant:	Tench and White	Examiner:	VAN, Luan V.
Filed:	09/26/2003	TC/A.U.:	1753
Title:	Improved Copper Bath for Electroplating Fine Circuitry on Semiconductor Chips	O.A. Date:	January 23, 2006
		Resp. Date:	May 23, 2006

Docket No.: 03RSC004

Customer No.: 56294

Mail Stop AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

REPLY UNDER 37 CFR 1.116

Sir:

In response to the Office Action of January 23, 2006, please amend the above-identified application as follows:

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims are not included herein, but a complete listing of the claims begins on page 3 of this paper.

Amendments to the Drawings are not included herein.

Remarks begin on page 8 of this paper.

A Petition for Extension of Time begins on page 10 of this paper.

A Petition to Claim Priority begins on page 10 of this paper.